mmWave SiP Technology & Challenges
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Millimeter-wave (mmWave) band from 28 GHz up to 300GHz has been identified as an important technology to provide extreme throughput, low latency, high resolution for applications: fifth-generation (5G) mobile communications (28/39GHz band), 802.11ad (60GHz band) and automotive radar (77/79GHz band).

System in Package (SiP) provides the user of the above applications the comprehensive solutions to optimize and differentiate their products to meet the system requirement.

This talk will give innovations in SiP technologies: Organic substrate, Fan-out, Hybrid Passives (HyPas),... etc, describing how these solutions are verified in achieving higher bandwidth connectivity, smaller form factor, increased functionality, mixed nodes, so very important in the mobile & big data applications.